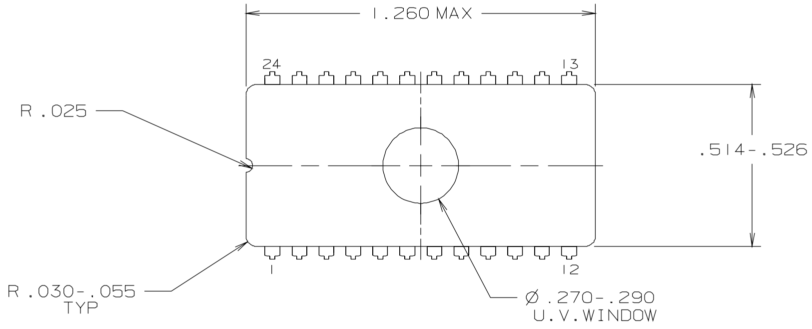
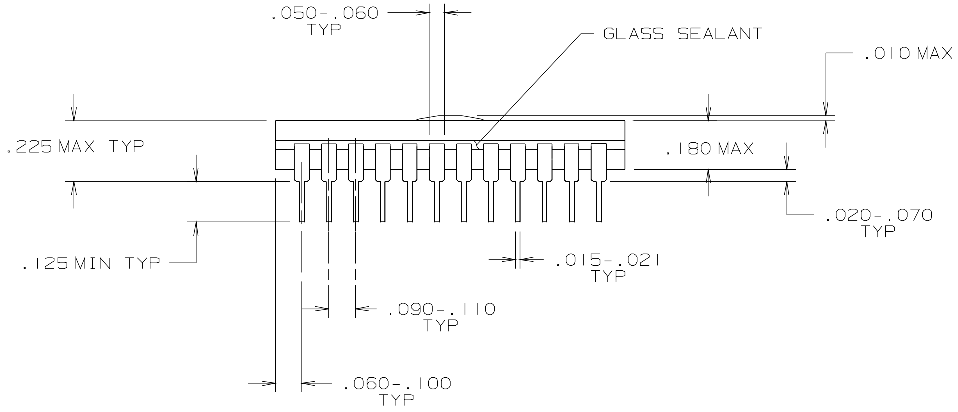
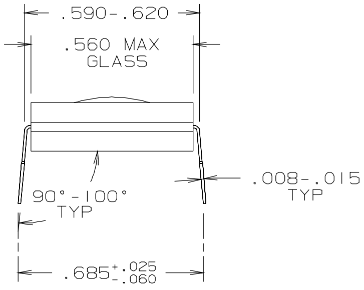
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
G	REVISE AND REDRAW	09001	01/08/92	DEG/







MIL/AERO
CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
   - a) 200 MICROINCHES MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
   - b) 200-800 MICROINCHES TIN PLATE OVER 50-300 MICROINCHES NICKEL UNDERPLATE OR BASIS METAL.
   - c) 50-100 MICROINCHES GOLD OVER 50-350 MICROINCHES NICKEL UNDERPLATE.
2. LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
3. NO JEDEC REGISTRATION AS OF 12/16/91.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION 2900 Semiconductor Drive, Santa Clara, CA 95052-8090
DRAWN D.E.GRADY	01/08/92	CERDIP (JQ), 24 LEAD, EPROM, SMALL WINDOW
DFTG. CHK.		
ENGR. CHK.		
APPROVAL		
PROJECTION INCH MM		SCALE N/A · SIZE C · DRAWING NUMBER MKT-J24AQ · REV G FORMERLY: N/A · SHEET 1 OF 1